EAST SEARCH FOR 10-773,863

	Туре	L#	Hits	Search Text	DBs
1	BRS	L1	1155	semiconductor adj (exhaust or waste or offgas)	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWEN
2	BRS	L2	145018	((high adj temperature) or hot) adj air	US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWEN
3	BRS	L3	4		US- PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWEN

	Time Stamp	Comments	Error Definition	Err
1	2006/11/20 08:49			
2	2006/11/20 08:50			
3	2006/11/20 08:50			

DERWENT- 200

2006-327021

ACC-NO:

DERWENT-

200634

WEEK:

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TITLE:

Method for increasing purification efficiency of exhaust from a semiconductor production process comprises ejecting hot air at the exhaust outlet end in an exhaust treatment tank for directly fully purifying harmful material in the

exhaust

INVENTOR: FENG, W

PATENT-ASSIGNEE: ORIENT SERVICE CO LTD[ORIEN]

PRIORITY-DATA: 2003TW-0103924 (February 25, 2003)

PATENT-FAMILY:

PUB-NO PUB-DATE LANGUAGE PAGES MAIN-IPC

TW 230240 B1 April 1, 2005 N/A 000 F23G 007/06

TW 200416369 A September 1, 2004 N/A 000 F23G 007/06

APPLICATION-DATA:

PUB-NO APPL-DESCRIPTOR APPL-NO APPL-DATE

TW 230240B1 N/A 2003TW-0103924 February 25, 2003

TW 200416369A N/A 2003TW-0103924 February 25, 2003

INT-CL (IPC): F23G007/06

ABSTRACTED-PUB-NO: TW 200416369A

BASIC-ABSTRACT:

NOVELTY - A method for increasing the purification efficiency of an exhaust from a semiconductor production process mainly comprises:

forcedly ejecting a <u>hot air</u> at the exhaust outlet end in an exhaust treatment tank for directly fully purifying harmful material in the exhaust by using the feature where the <u>hot air</u> has an optimal catalytic temperature at the outlet end, thereby increasing the purification efficiency of the <u>semiconductor exhaust</u>.

CHOSEN-

Dwg.0/0

DRAWING:

TITLE-

METHOD INCREASE PURIFICATION EFFICIENCY EXHAUST

TERMS:

SEMICONDUCTOR PRODUCE PROCESS COMPRISE EJECT HOT AIR EXHAUST OUTLET END EXHAUST TREAT TANK PURIFICATION HARM

EARAODI OOTUBI EMD EARAODI IRBAI IAWA TORIIICAIIA

MATERIAL EXHAUST

DERWENT-CLASS: Q73

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N2006-276818

DERWENT- 2006-654260

ACC-NO:

DERWENT- 200668

WEEK:

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TITLE: Method for cleaning harmful materials of semiconductor

waste gas to accelerate chemical reaction of harmful

materials included in semiconductor waste gas

INVENTOR: FENG, W N

PATENT-ASSIGNEE: FENG W N[FENGI]

PRIORITY-DATA: 2004KR-0009264 (February 12, 2004)

PATENT-FAMILY:

PUB-NO PUB-DATE LANGUAGE PAGES MAIN-IPC

KR 2005081035 A August 18, 2005 N/A 000 H01L 021/02

APPLICATION-DATA:

PUB-NO APPL-DESCRIPTOR APPL-NO APPL-DATE

KR2005081035A N/A 2004KR-0009264 February 12, 2004

INT-CL (IPC): H01L021/02

ABSTRACTED-PUB-NO: KR2005081035A

BASIC-ABSTRACT:

NOVELTY - A method for cleaning harmful materials of <u>semiconductor</u> waste gas is provided to accelerate a chemical reaction of harmful materials included in <u>semiconductor waste</u> gas by guiding <u>high</u> temperature air to an outlet of waste gas of a semiconductor gas reducing system.

DETAILED DESCRIPTION <u>- Hot air (30)</u> is injected into a waste gas outlet (13) of a semiconductor gas reducing system(1). The <u>hot air</u> is

sent to <u>semiconductor waste</u> gas(4) exhausted from the waste gas outlet to accelerate the reaction of harmful materials in the <u>semiconductor waste</u> gas. The <u>hot air</u> is generated from a <u>hot air</u> generating unit(2).(C) KIPO 2006Image 1/1

CHOSEN-

Dwg.1/1

DRAWING:

TITLE-

METHOD CLEAN HARM MATERIAL SEMICONDUCTOR WASTE GAS

TERMS:

ACCELERATE CHEMICAL REACT HARM MATERIAL SEMICONDUCTOR

WASTE GAS

DERWENT-CLASS: U11

EPI-CODES: U11-C15Q;